

Small Outline Packages SOIC

Suchi Semicon Offers

Small Outline Integrated Circuit (SOIC) is a type of surface-mount electronic component package used for integrated circuits (ICs)

Compact Size: 30% less area and 70% thinner than DIP.

Lead Configuration: SOIC packages have “gull wing” leads that extend from the two longer sides of the rectangular body.

Pin Spacing: The leads are spaced at 1.27 mm (0.050 inches) apart, which is standard for SOIC packages.

Variants

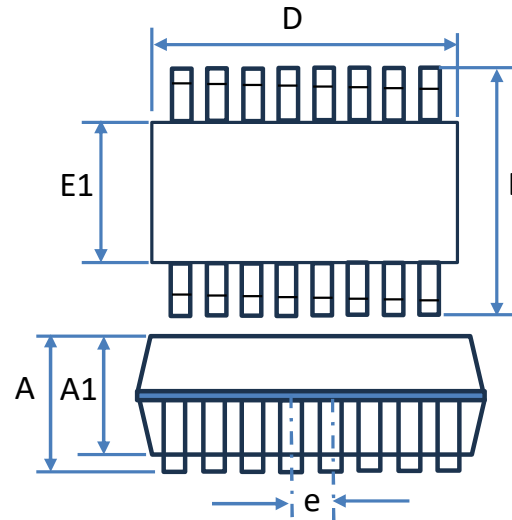
- **By Lead Count**

- **SOIC-8** : 8 leads
- **SOIC-14**: 14 leads
- **SOIC-16**: 16 leads
- **SOIC-20**: 20 leads
- **SOIC-24**: 24 leads
- **SOIC-28**: 28 leads

- **By Width**

- **Narrow SOIC (SOIC-N)**
Body width of 3.9mm
- **Wide SOIC (SOIC-W)**
Body width of 7.5mm

- **MSL Level 1**
- **Zero Delamination Process**
- **AECQ100/101 Qualification Options**
- **ROHS Compliance**



Narrow Body			
Pitch = 1.27mm, Body Width = 3.90mm			
A	1.75 max		
A1	1.2 Min		
E	6.00		
E1	3.90		
e	1.27		
D	4.90	8.65	9.90
Leads	8	14	16

Wide Body						
Pitch = 1.27mm, Body Width = 7.50mm						
A	2.65 max					
A1	2.05 Min					
E	10.30					
E1	7.50					
e	1.27					
D	9.00	10.30	11.55	12.80	15.40	17.90
Leads	14	16	18	20	24	28